- **Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs**
- **Dependable Texas Instruments Quality and Reliability**

description

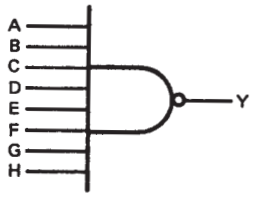
These devices contain a single 8-input NAND gate.

The SN5430, SN54LS30, and SN54S30 are characterized for operation over the full military range of −55°C to 125°C. The SN7430, SN74LS30, and SN74S30 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE

INPUTS A THRU H	OUTPUT Y
All inputs H	L
One or more inputs L	H

logic diagram

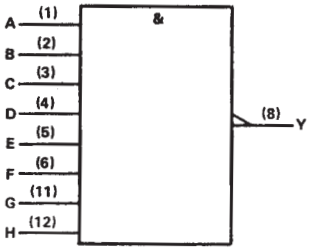


positive logic

$$Y = \overline{A \cdot B \cdot C \cdot D \cdot E \cdot F \cdot G \cdot H} \quad \text{or}$$

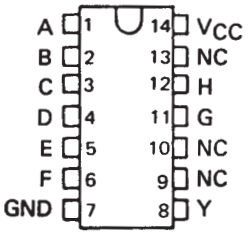
$$Y = \overline{A} + \overline{B} + \overline{C} + \overline{D} + \overline{E} + \overline{F} + \overline{G} + \overline{H}$$

logic symbol†

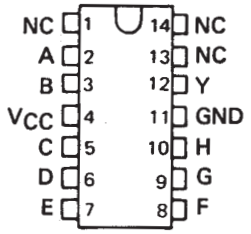


†This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, and W packages.

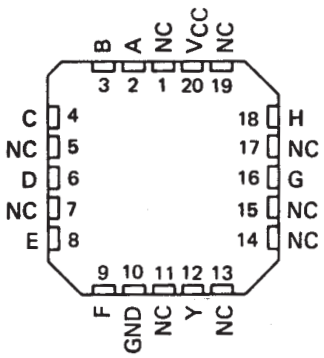
SN5430 . . . J PACKAGE
SN54LS30, SN54S30 . . . J OR W PACKAGE
SN7430 . . . N PACKAGE
SN74LS30, SN74S30 . . . D OR N PACKAGE
(TOP VIEW)



SN5430 . . . W PACKAGE
(TOP VIEW)



SN54LS30, SN54S30 . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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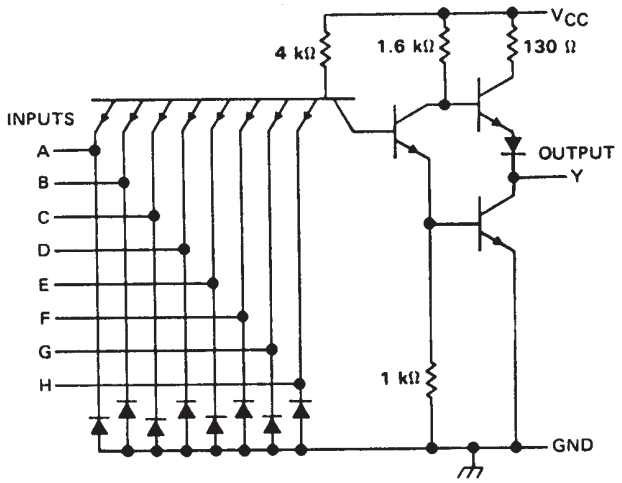
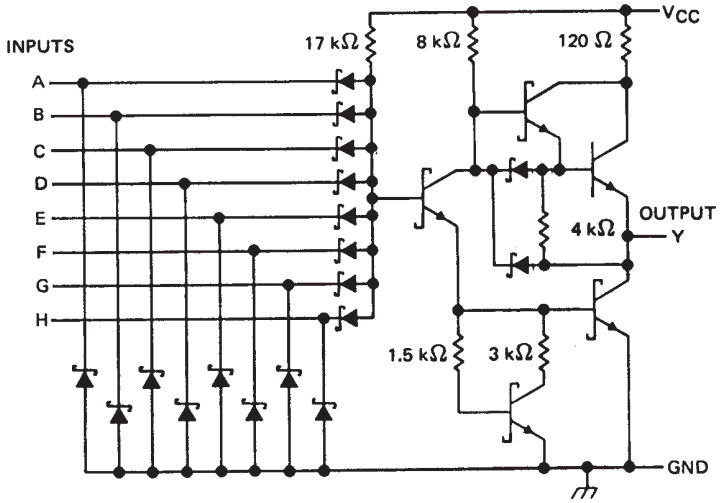
schematics (each gate)

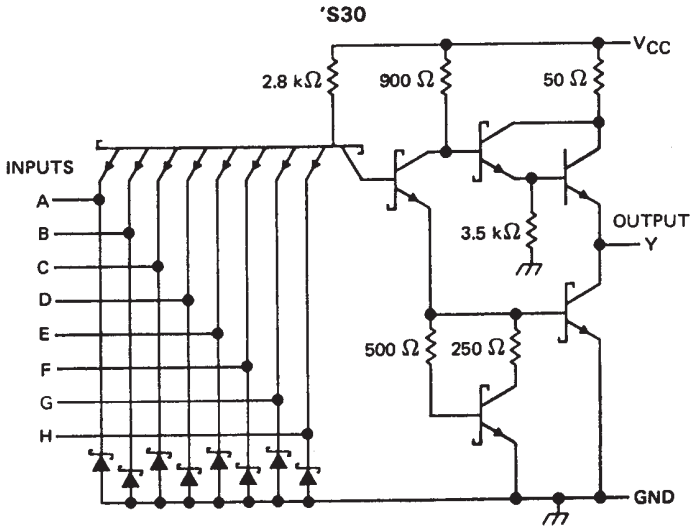
'30



'LS30



'S30



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 5.5 V
Operating free-air temperature range: SN5430 . . . . . −55°C to 125°C
SN7430 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN5430			SN7430			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{OH}	High-level output current			−0.4			−0.4	mA
I_{OL}	Low-level output current			16			16	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †			SN5430			SN7430			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN,	I_I = −12 mA				−1.5			−1.5	V
V_{OH}	V_{CC} = MIN,	V_{IL} = 0.8 V,	I_{OH} = −0.4 mA	2.4	3.4		2.4	3.4		V
V_{OL}	V_{CC} = MIN,	V_{IH} = 2 V,	I_{OL} = 16 mA		0.2	0.4		0.2	0.4	V
I_I	V_{CC} = MAX,	V_I = 5.5 V				1			1	mA
I_{IH}	V_{CC} = MAX,	V_I = 2.4 V				40			40	μA
I_{IL}	V_{CC} = MAX,	V_I = 0.4 V				−1.6			−1.6	mA
I_{OS}§	V_{CC} = MAX			−20		−55	−18		−55	mA
I_{CCH}	V_{CC} = MAX,	V_I = 0			1	2		1	2	mA
I_{CCL}	V_{CC} = MAX,	V_I = 4.5 V			3	6		3	6	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	Any	Y	R_L = 400 Ω,	C_L = 15 pF		13	22	ns
t_{PHL}						8	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 7 V
Operating free-air temperature range: SN54LS30 . . . . . −55°C to 125°C
SN74LS30 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54LS30			SN74LS30			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage			0.7			0.8	V
I_{OH} High-level output current			−0.4			−0.4	mA
I_{OL} Low-level output current			4			8	mA
T_A Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †	SN54LS30			SN74LS30			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN, I_I = −18 mA			−1.5			−1.5	V
V_{OH}	V_{CC} = MIN, V_{IL} = MAX, I_{OH} = −0.4 mA	2.5	3.4		2.7	3.4		V
V_{OL}	V_{CC} = MIN, V_{IH} = 2 V, I_{OL} = 4 mA		0.25	0.4			0.4	V
	V_{CC} = MIN, V_{IH} = 2 V, I_{OL} = 8 mA					0.25	0.5	
I_I	V_{CC} = MAX, V_I = 7 V			0.1			0.1	mA
I_{IH}	V_{CC} = MAX, V_I = 2.7 V			20			20	μA
I_{IL}	V_{CC} = MAX, V_I = 0.4 V			−0.4			−0.4	mA
I_{OS}§	V_{CC} = MAX	−20		−100	−20		−100	mA
I_{CCH}	V_{CC} = MAX, V_I = 0		0.35	0.5		0.35	0.5	mA
I_{CCL}	V_{CC} = MAX, V_I = 4.5 V		0.6	1.1		0.6	1.1	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C
§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Any	Y	R_L = 2 kΩ, C_L = 15 pF		8	15	ns
t_{PHL}					13	20	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 5.5 V
Operating free-air temperature range: SN54S30 . . . . . −55°C to 125°C
SN74S30 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54S30			SN74S30			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage			0.8			0.8	V
I_{OH} High-level output current			−1			−1	mA
I_{OL} Low-level output current			20			20	mA
T_A Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †	SN54S30			SN74S30			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN, I_I = −18 mA			−1.2			−1.2	V
V_{OH}	V_{CC} = MIN, V_{IL} = 0.8 V, I_{OH} = −1 mA	2.5	3.4		2.7	3.4		V
V_{OL}	V_{CC} = MIN, V_{IH} = 2 V, I_{OL} = 20 mA			0.5			0.5	V
I_I	V_{CC} = MAX, V_I = 5.5 V			1			1	mA
I_{IH}	V_{CC} = MAX, V_I = 2.7 V			50			50	μA
I_{IL}	V_{CC} = MAX, V_I = 0.5 V			−2			−2	mA
I_{OS}§	V_{CC} = MAX	−40		−100	−40		−100	mA
I_{CCH}	V_{CC} = MAX, V_I = 0		3	5		3	5	mA
I_{CCL}	V_{CC} = MAX, V_I = 4.5 V		5.5	10		5.5	10	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Any	Y	R_L = 280 Ω, C_L = 15 pF		4	6	ns
t_{PHL}					4.5	7	ns
t_{PLH}			R_L = 280 Ω, C_L = 50 pF		5.5		ns
t_{PHL}					6.5		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
5962-9679201Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9679201QCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
5962-9679201QCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
5962-9679201QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
5962-9679201QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30009B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30009B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30009BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30009BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30009BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30009BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30009SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30009SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30009SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30009SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN5430J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN5430J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54LS30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54LS30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN7430N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7430N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS30D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
SN74LS30DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS30N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS30N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS30N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS30N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS30NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS30NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS30NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S30D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74S30D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74S30DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74S30DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74S30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74S30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74S30N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S30N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SNJ5430J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ5430J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ5430W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ5430W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS30FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS30FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS30W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS30W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S30FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S30FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SNJ54S30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S30W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S30W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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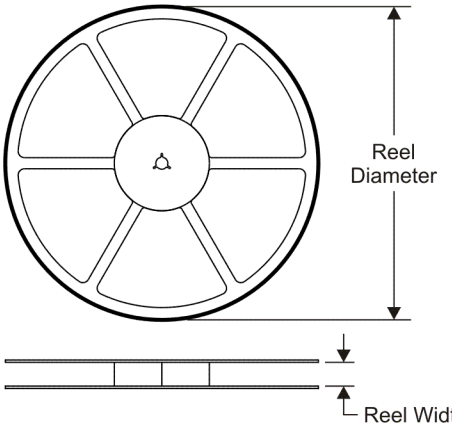
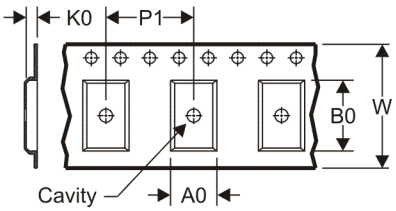
TAPE AND REEL INFORMATION

REEL DIMENSIONS

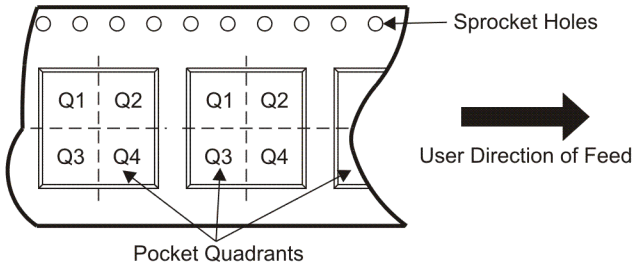


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

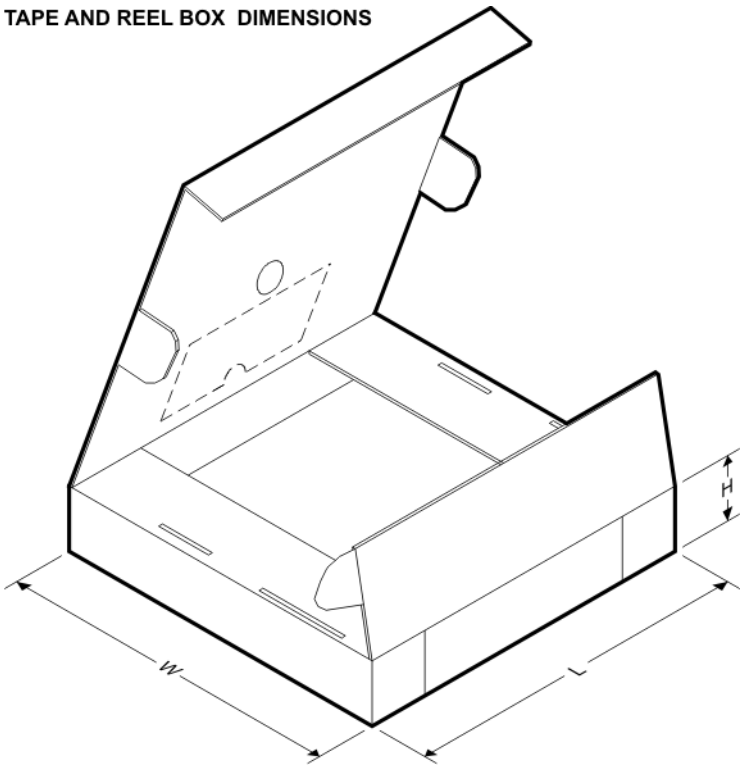
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS30DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS30NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



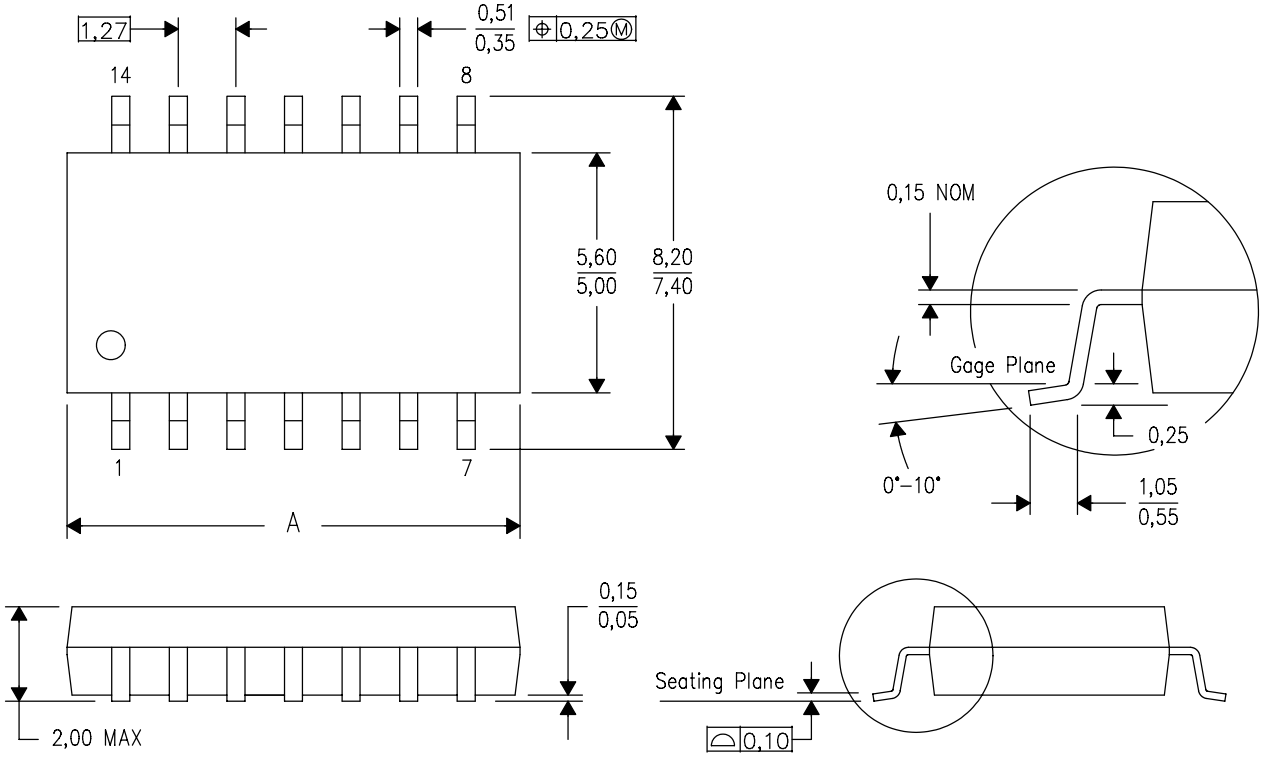
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS30DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS30NSR	SO	NS	14	2000	346.0	346.0	33.0

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



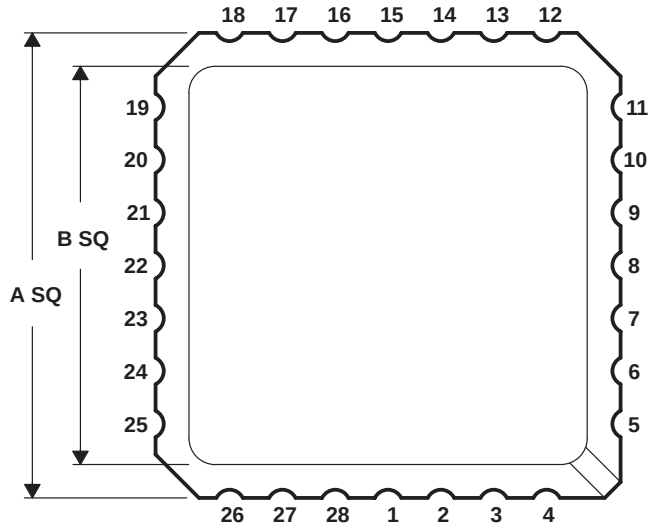
DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

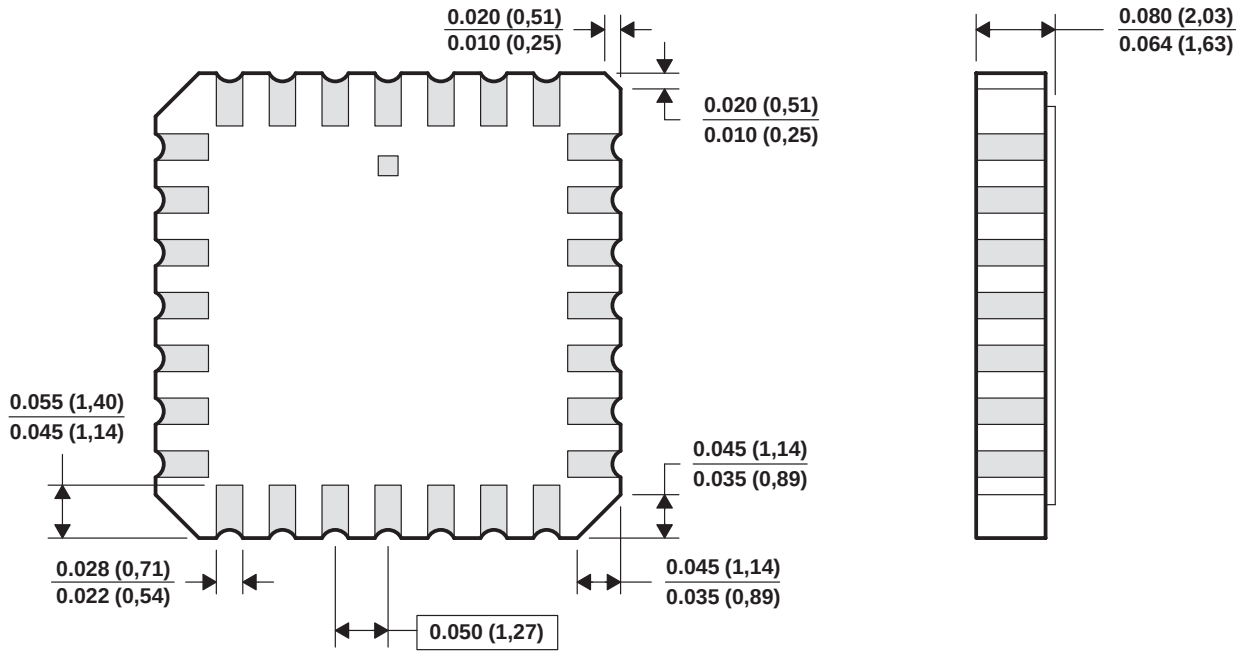
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

FK (S-CQCC-N)** **LEADLESS CERAMIC CHIP CARRIER**

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.739 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



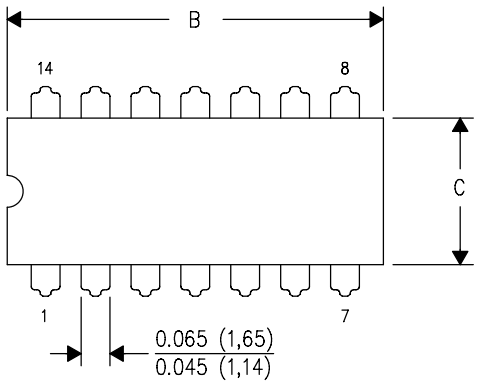
4040140/D 10/96

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. The terminals are gold plated.
E. Falls within JEDEC MS-004

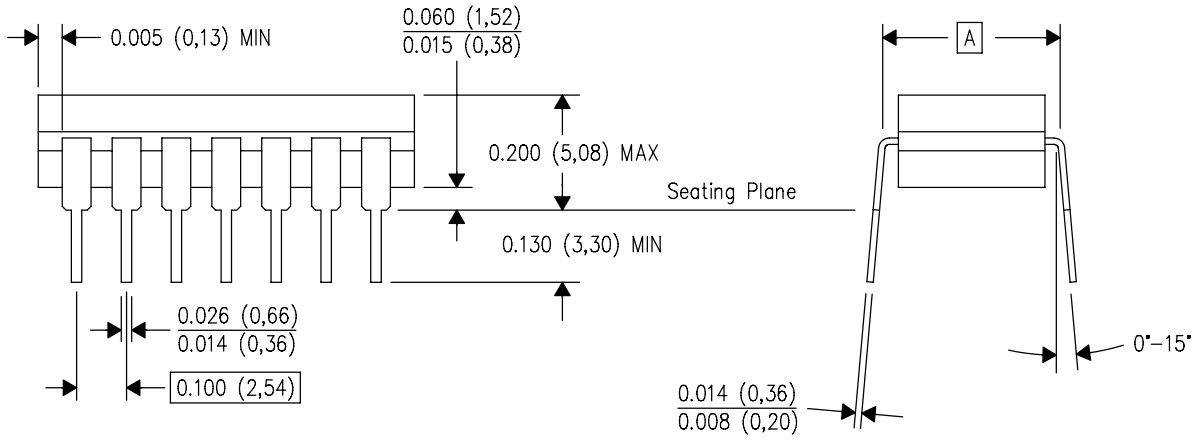
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



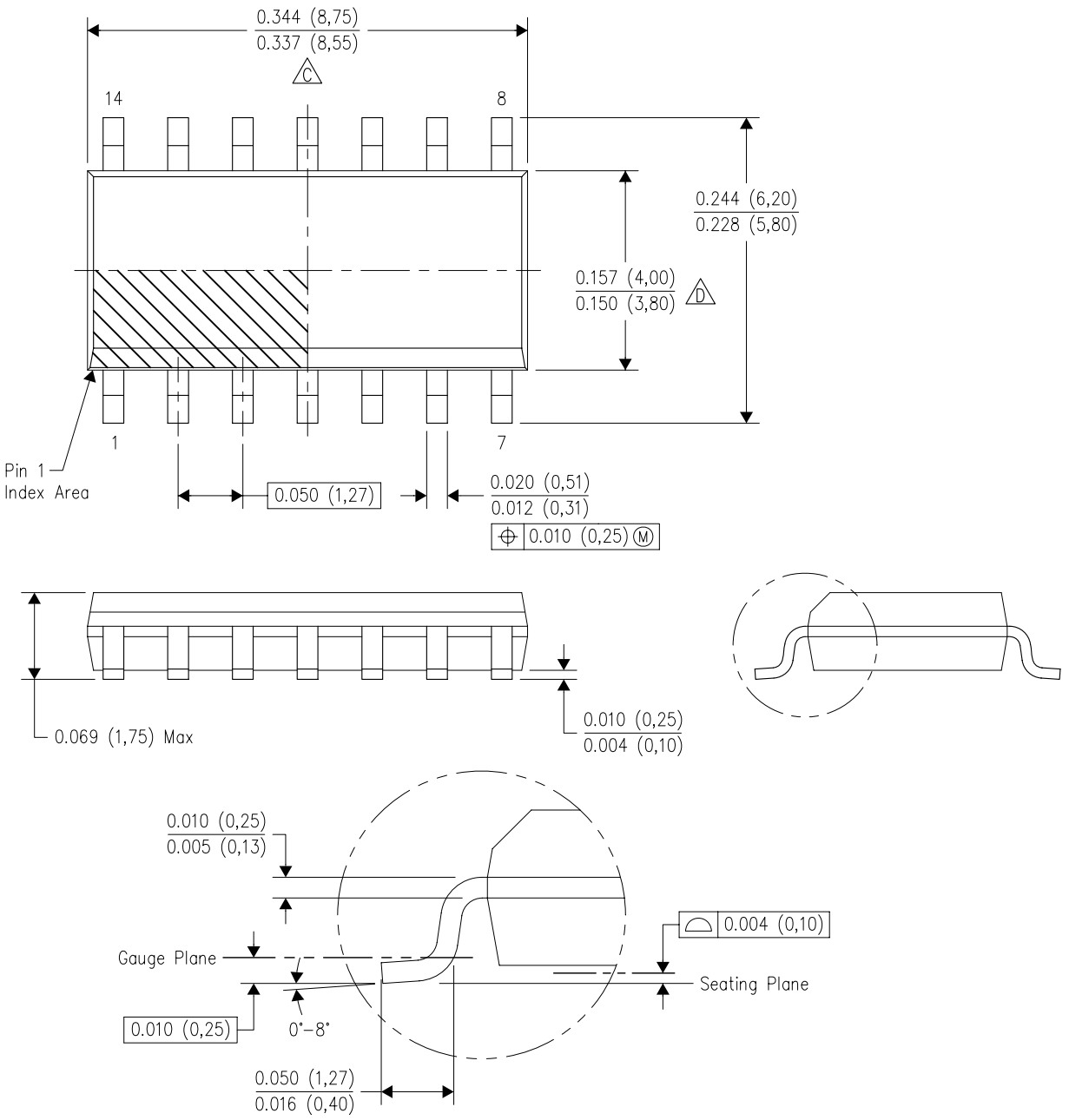
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

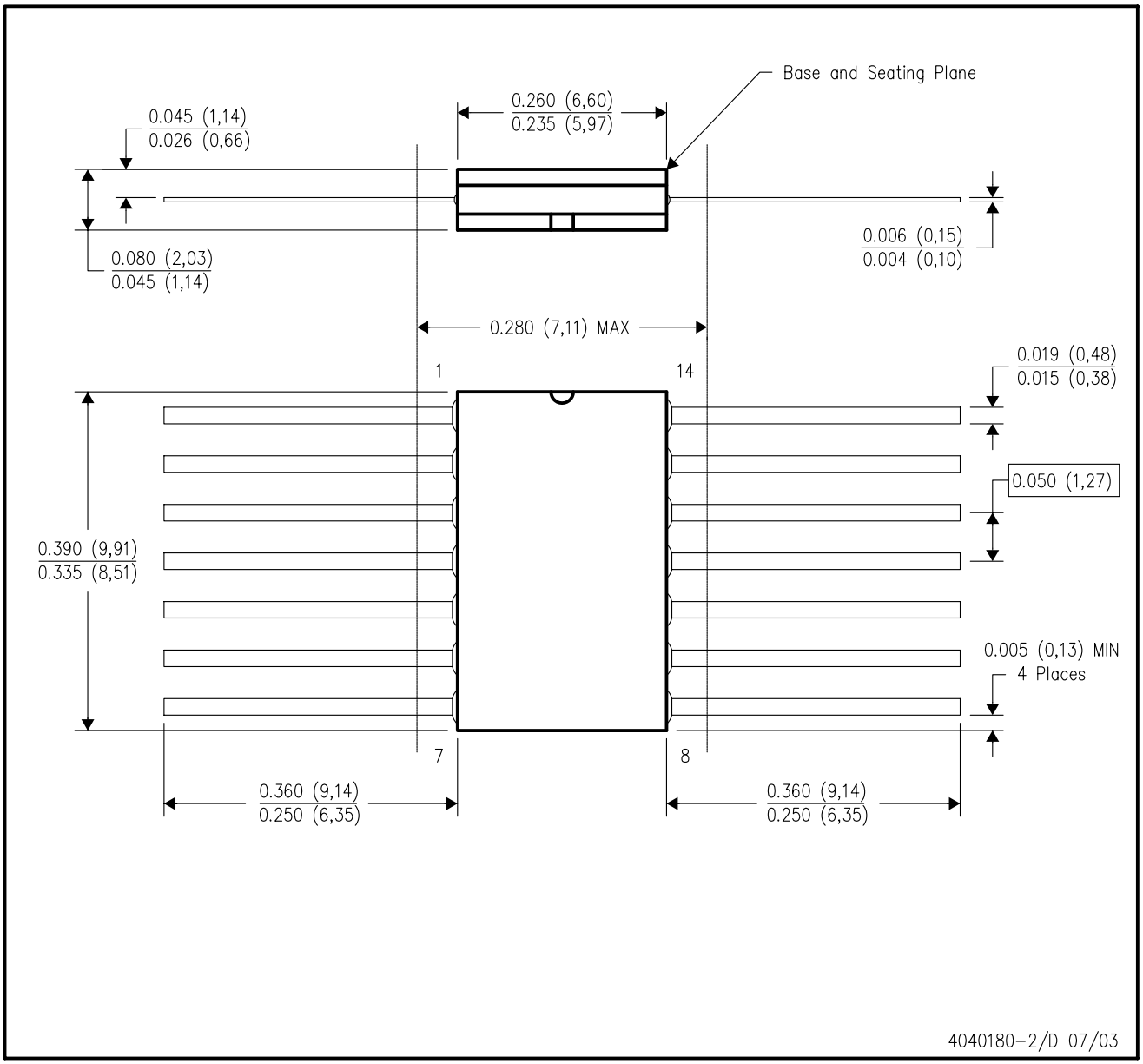
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

D (R–PDSO–G14) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS–012 variation AB.

W (R–GDFP–F14) CERAMIC DUAL FLATPACK

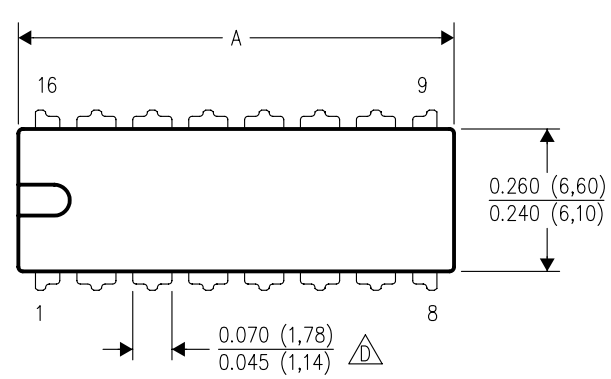


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14 and JEDEC MO–092AB

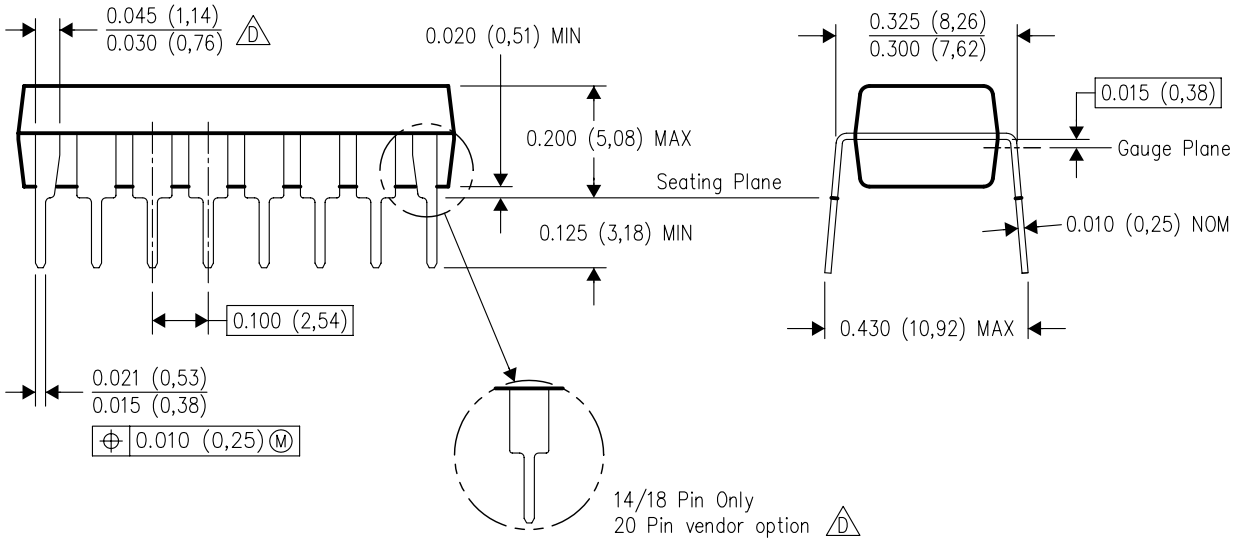
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
5962-9679201Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9679201QCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
5962-9679201QCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
5962-9679201QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
5962-9679201QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30009B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30009B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30009BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30009BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30009BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30009BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30009SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30009SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30009SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30009SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN5430J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN5430J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54LS30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54LS30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN7430N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7430N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS30D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
SN74LS30DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS30N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS30N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS30N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS30N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS30NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS30NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS30NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S30D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74S30D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74S30DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74S30DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74S30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74S30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74S30N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S30N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SNJ5430J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ5430J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ5430W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ5430W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS30FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS30FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS30W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS30W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S30FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S30FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SNJ54S30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S30W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S30W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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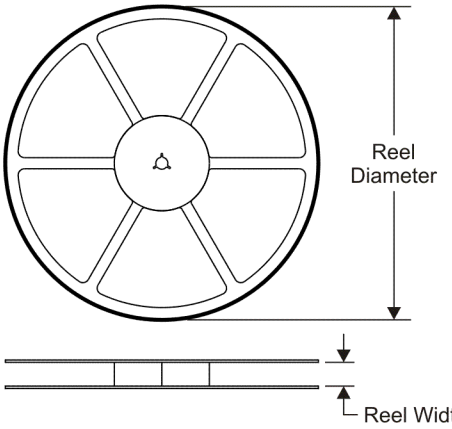
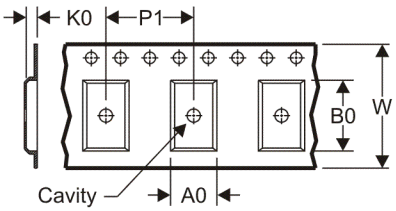
TAPE AND REEL INFORMATION

REEL DIMENSIONS

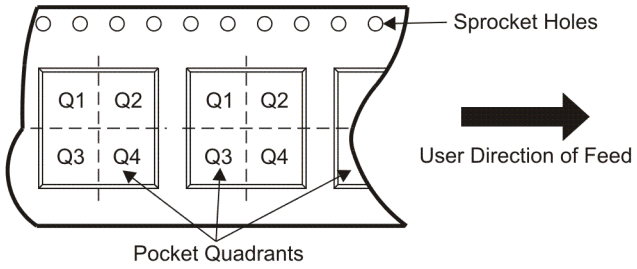


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

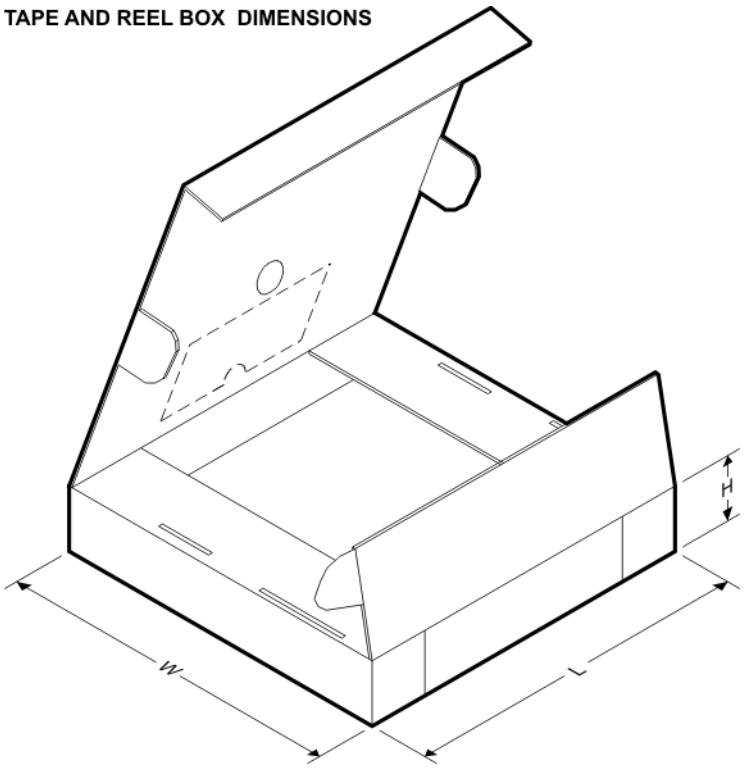
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS30DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS30NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

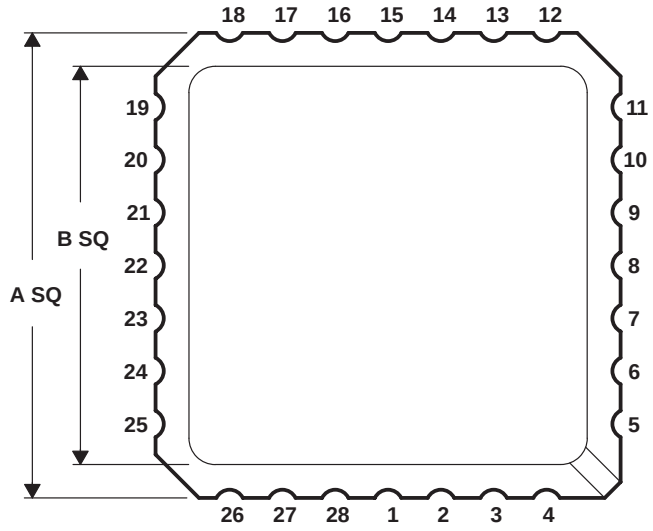


*All dimensions are nominal

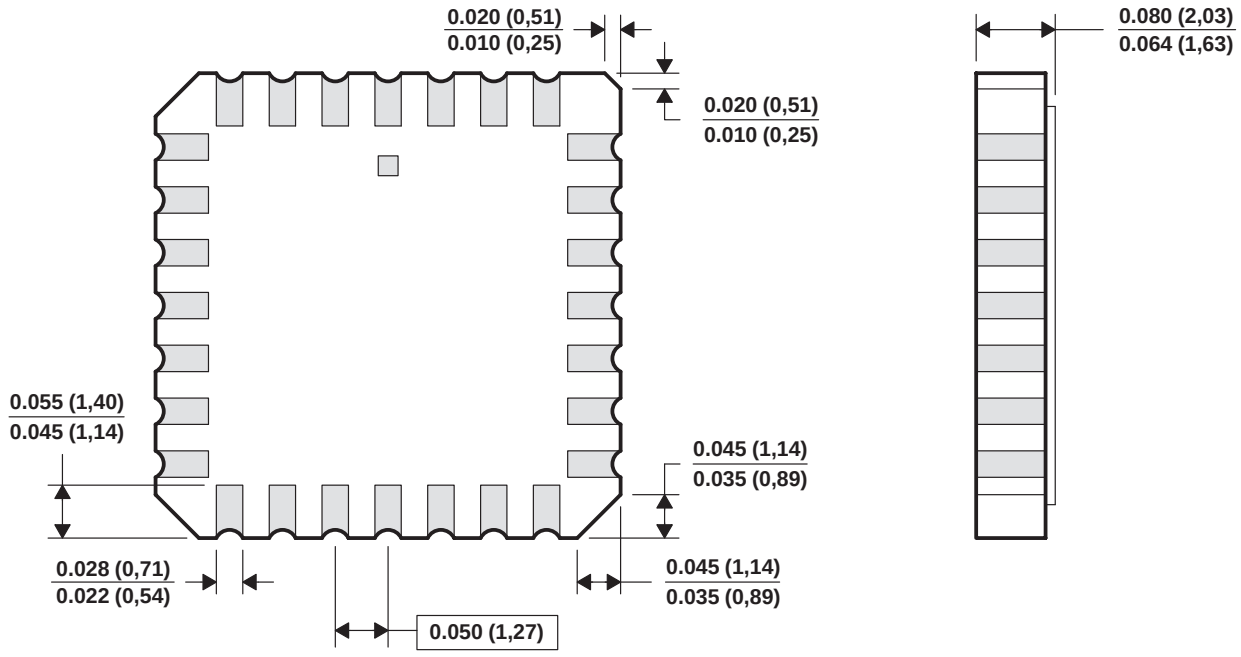
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS30DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS30NSR	SO	NS	14	2000	346.0	346.0	33.0

FK (S-CQCC-N)** **LEADLESS CERAMIC CHIP CARRIER**

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.739 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



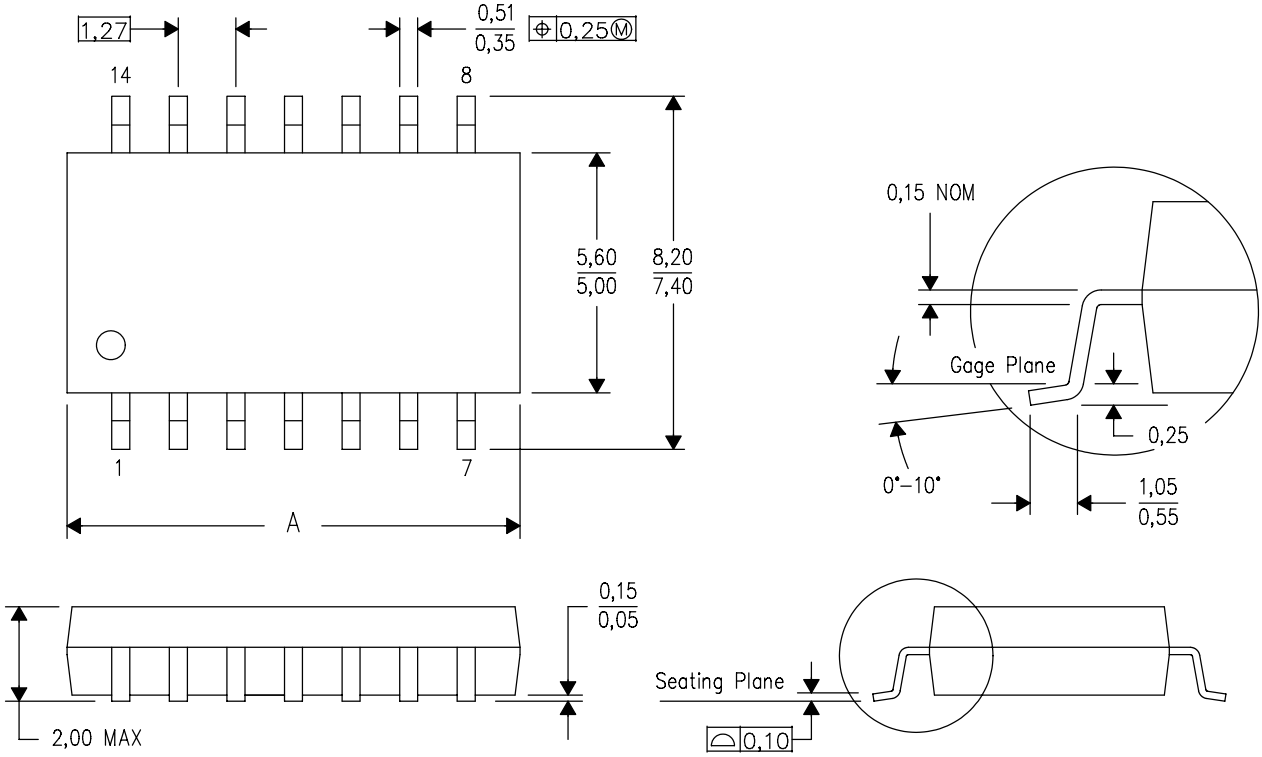
4040140/D 10/96

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. The terminals are gold plated.
E. Falls within JEDEC MS-004

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

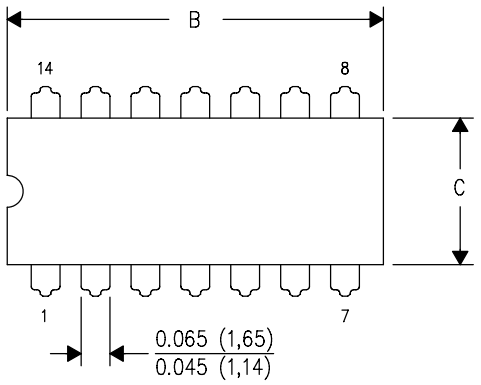
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

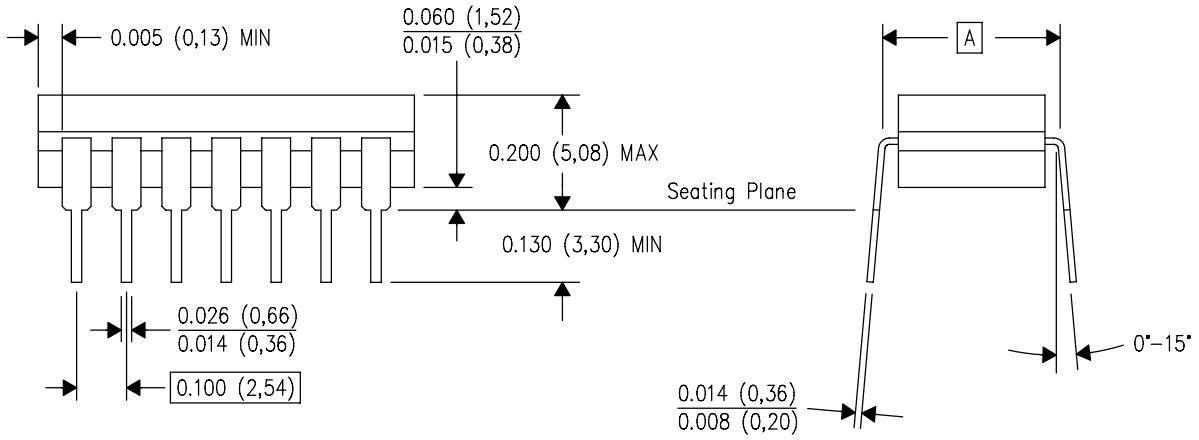
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



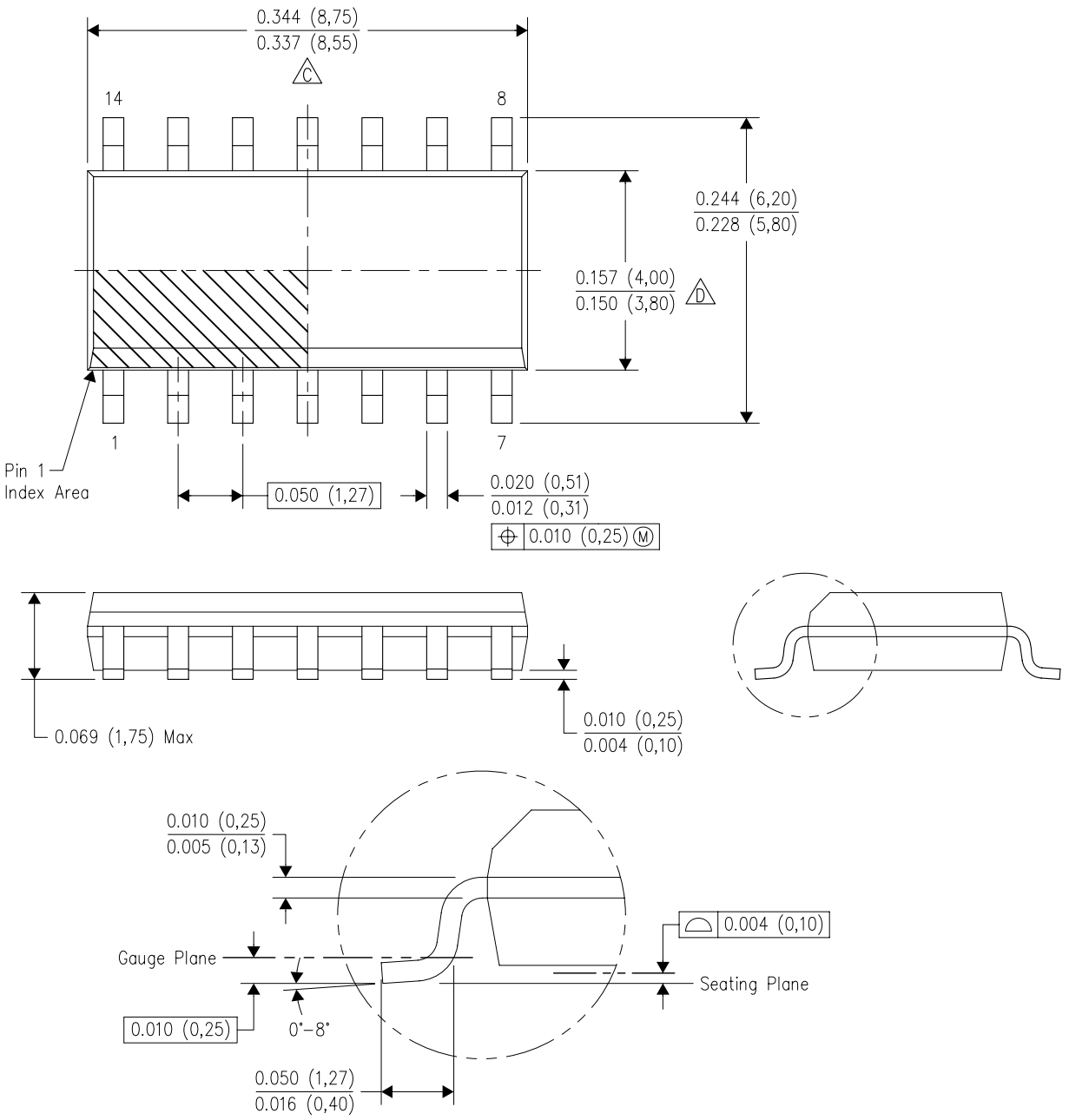
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

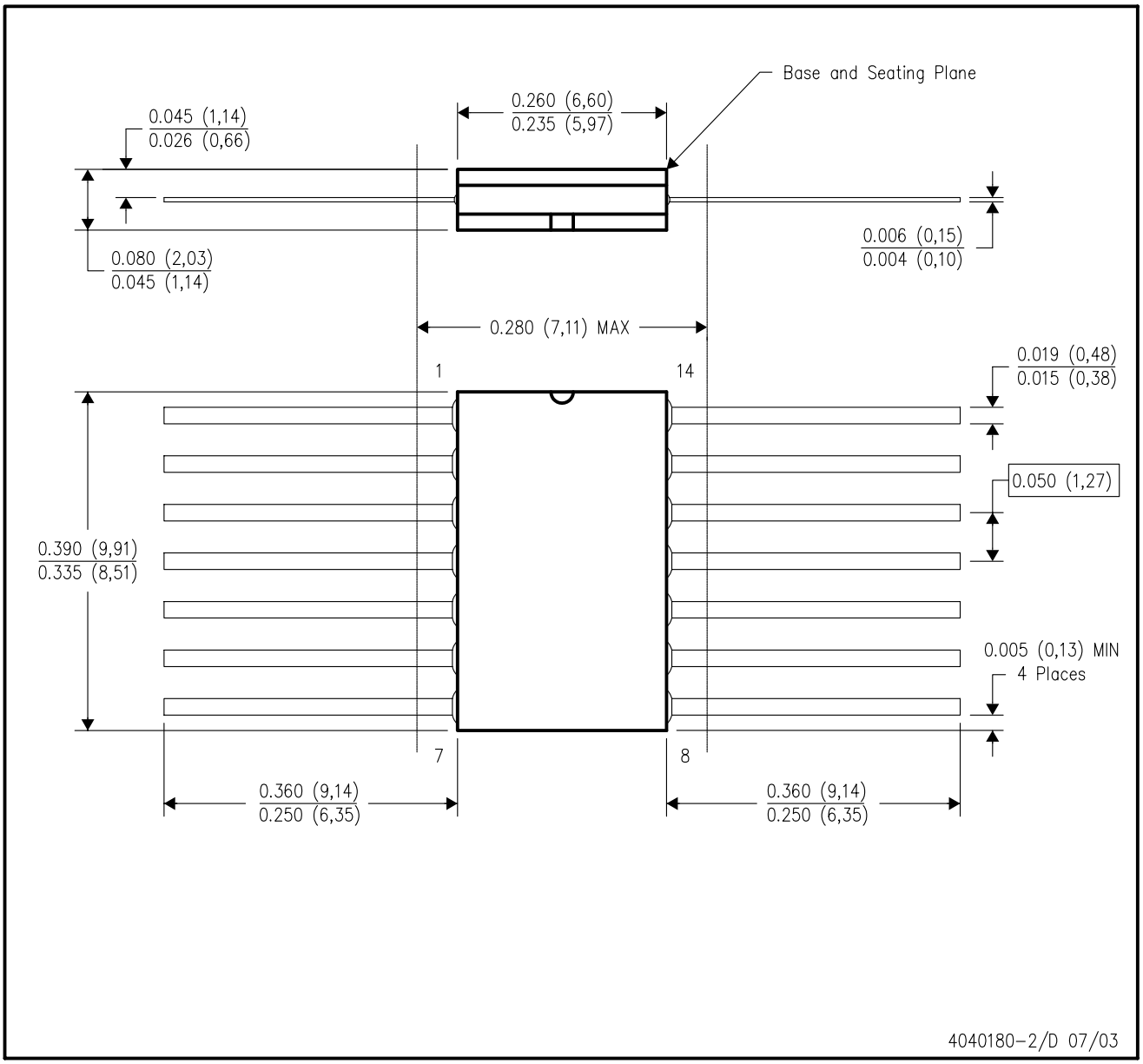
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

D (R–PDSO–G14) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS–012 variation AB.

W (R–GDFP–F14) CERAMIC DUAL FLATPACK

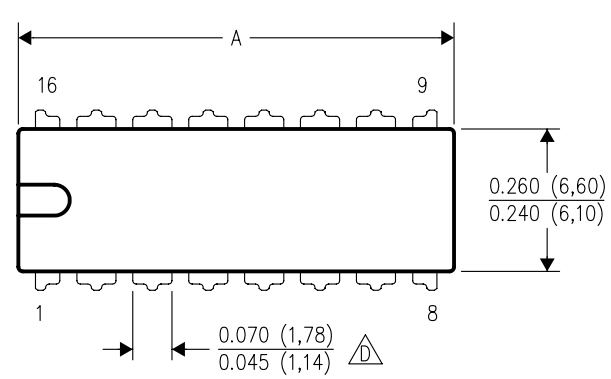


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14 and JEDEC MO–092AB

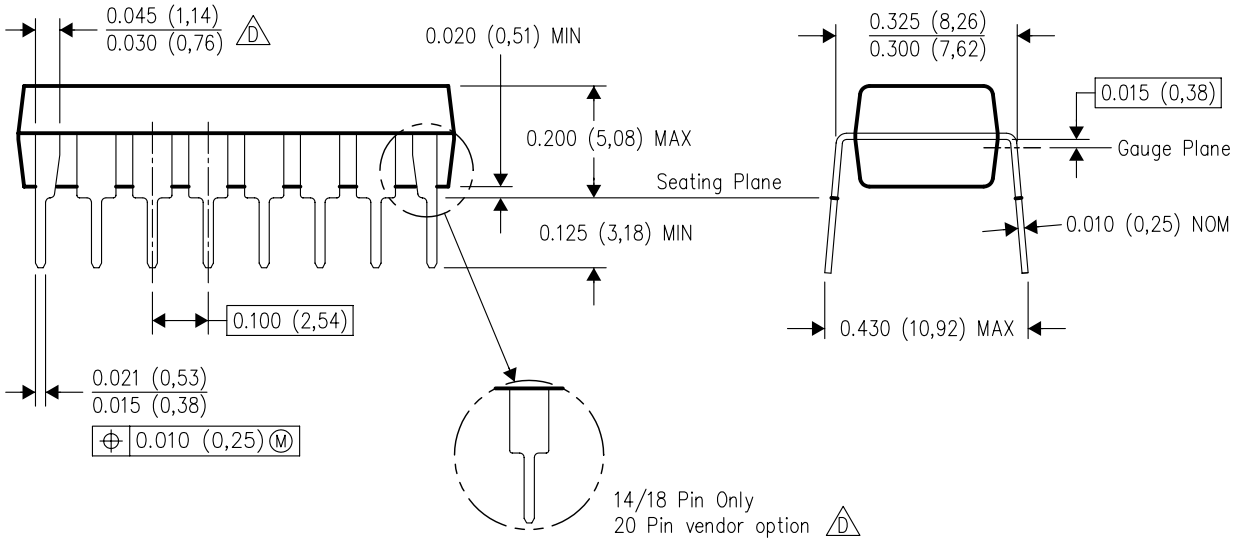
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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